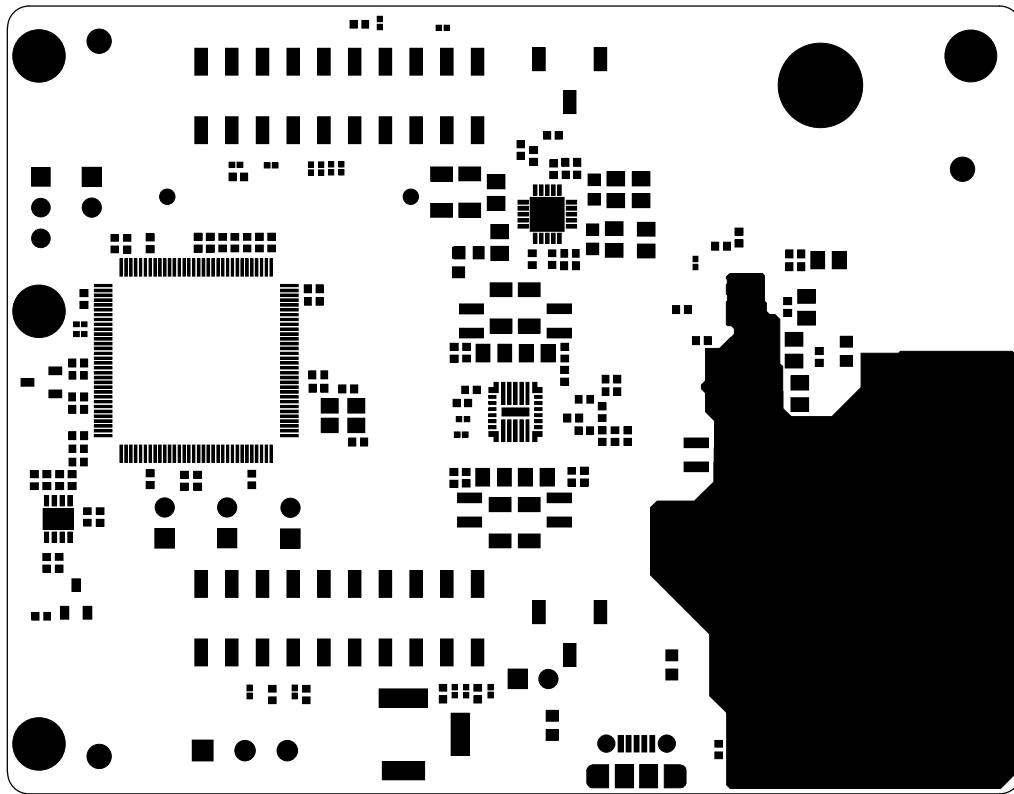

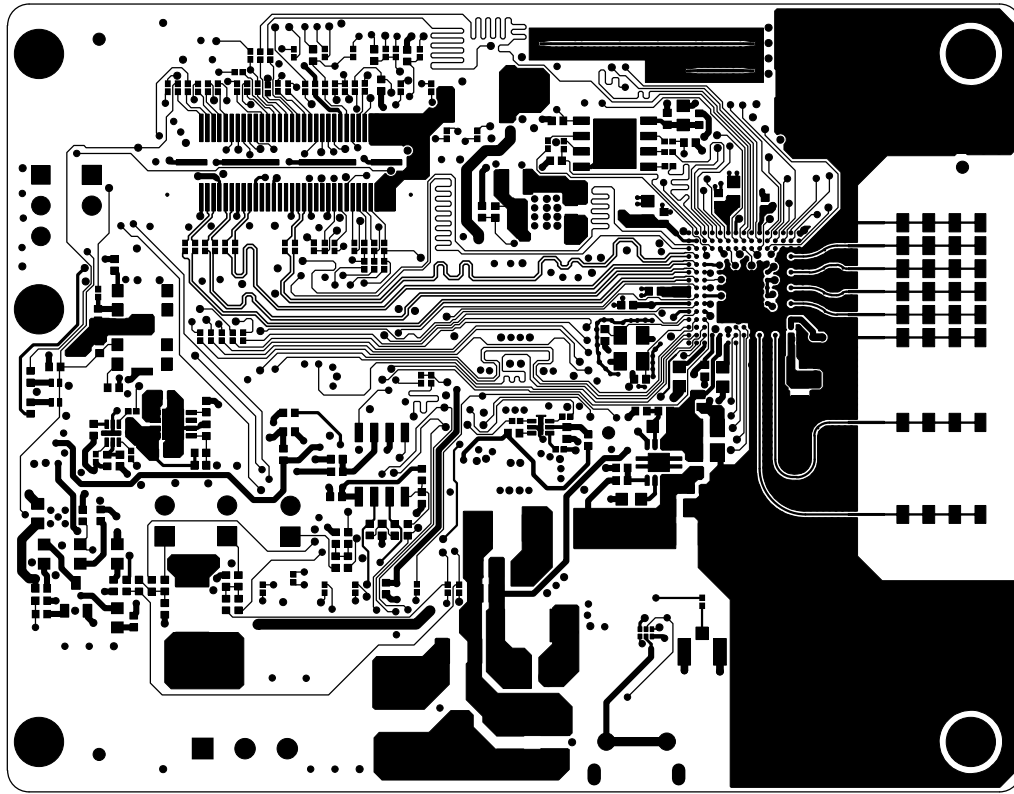

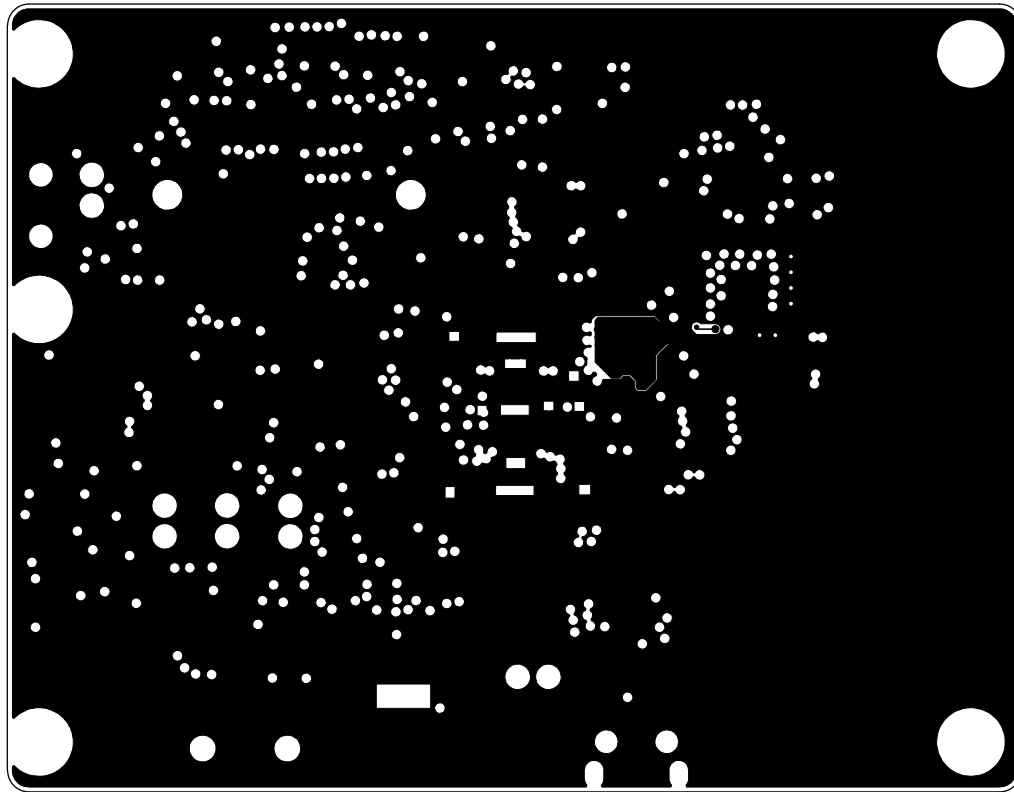
 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	SILKSCREEN TOP	1642-EVM Rev-A
	DATE: 02/MARCH/2017	




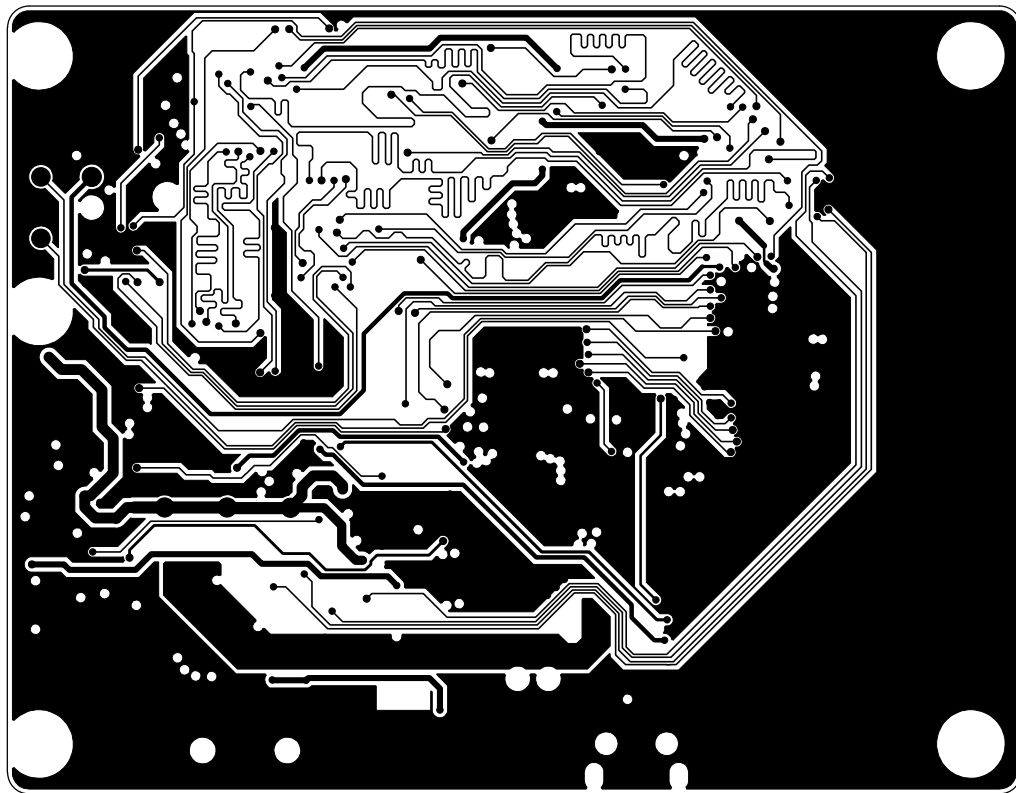
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	SOLDERMASK BOTTOM	1642-EVM Rev-A
	DATE: 02/MARCH/2017	




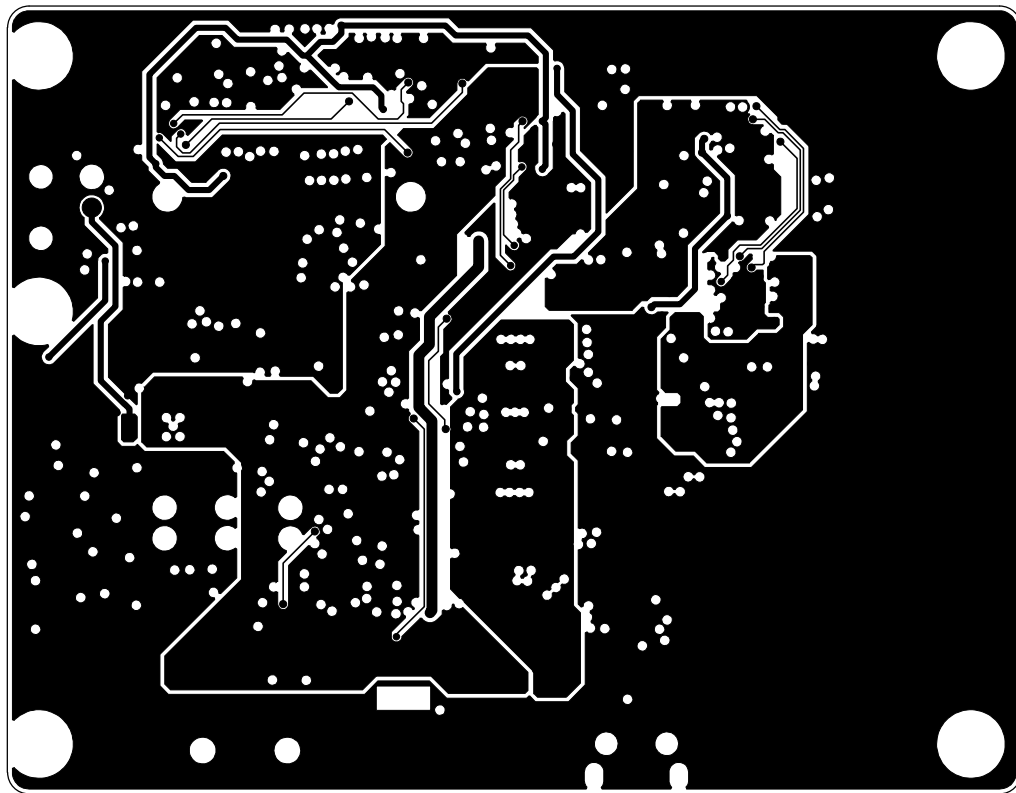
 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	LAYER-1 TOP	1642-EVM Rev-A
	DATE: 02/MARCH/2017	




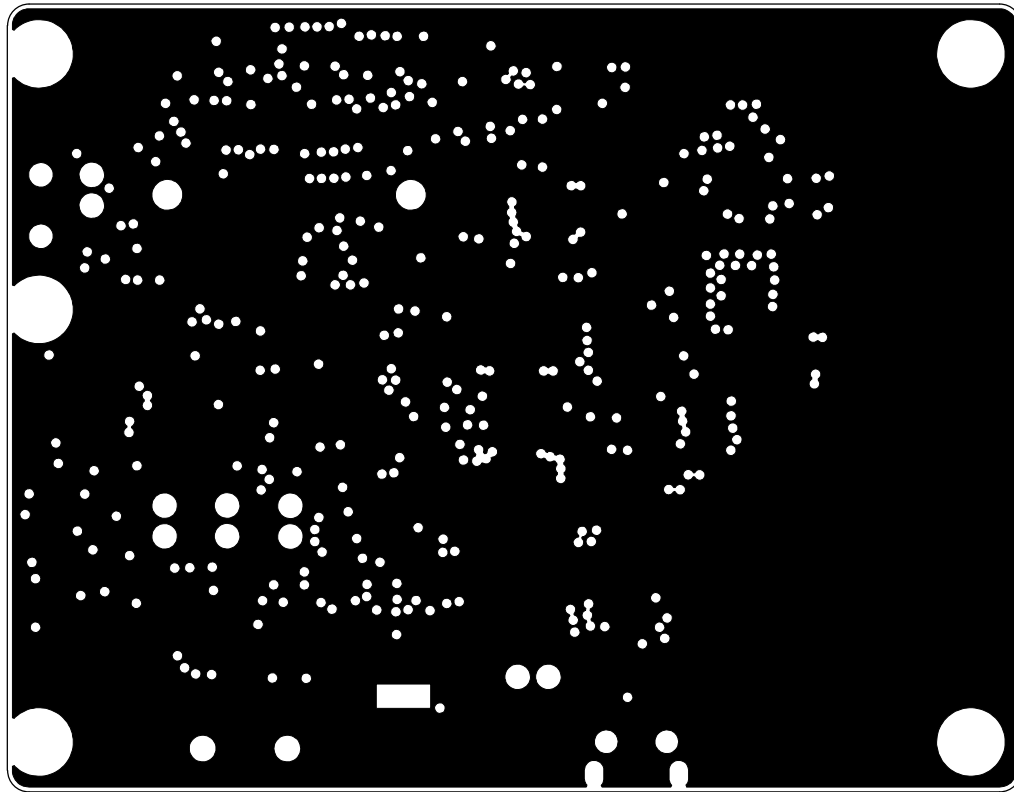
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	DATE: 02/MARCH/2017	




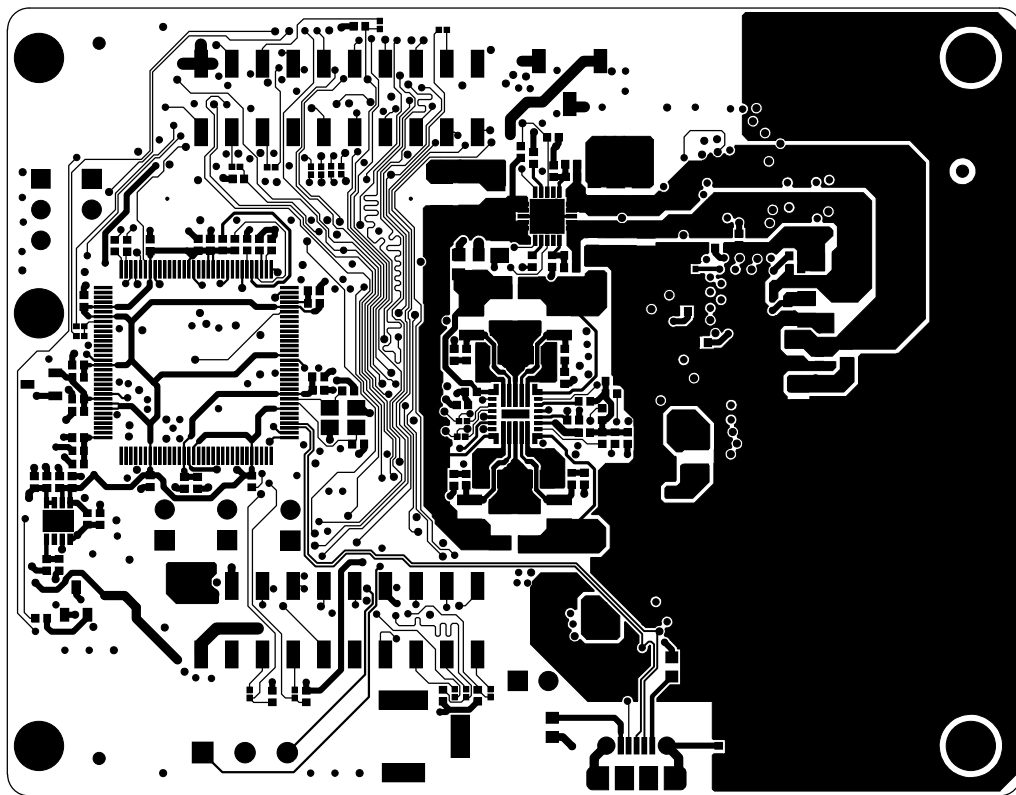
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	DATE: 02/MARCH/2017	




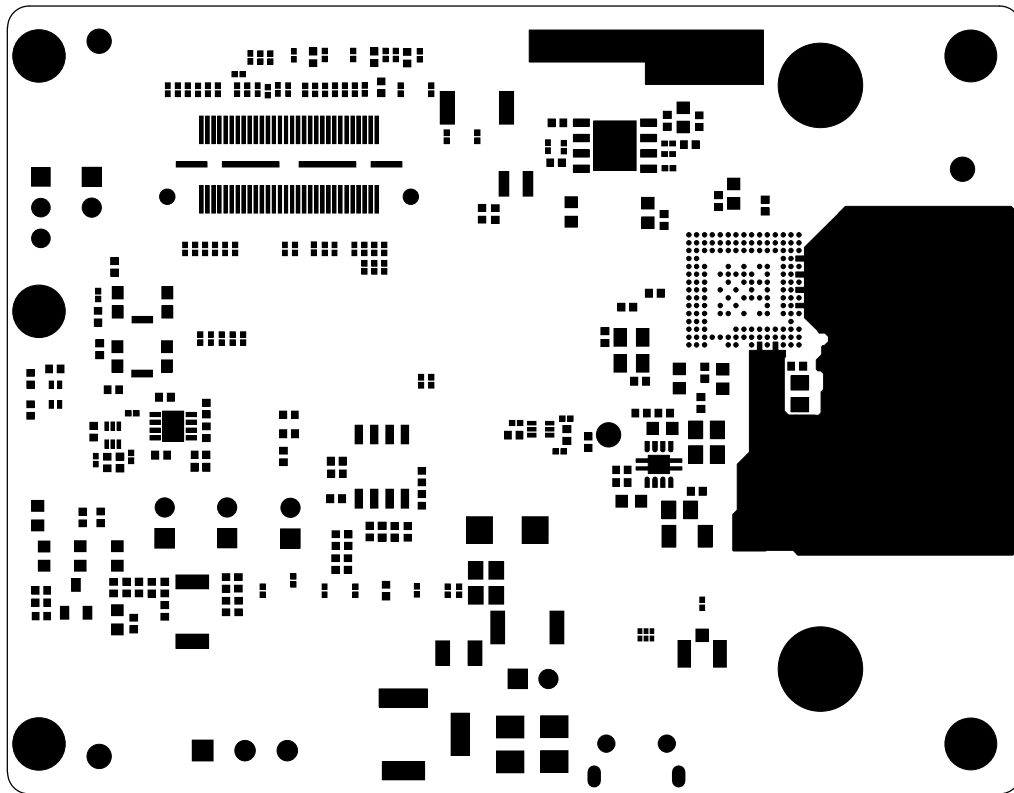
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	DATE: 02/MARCH/2017	




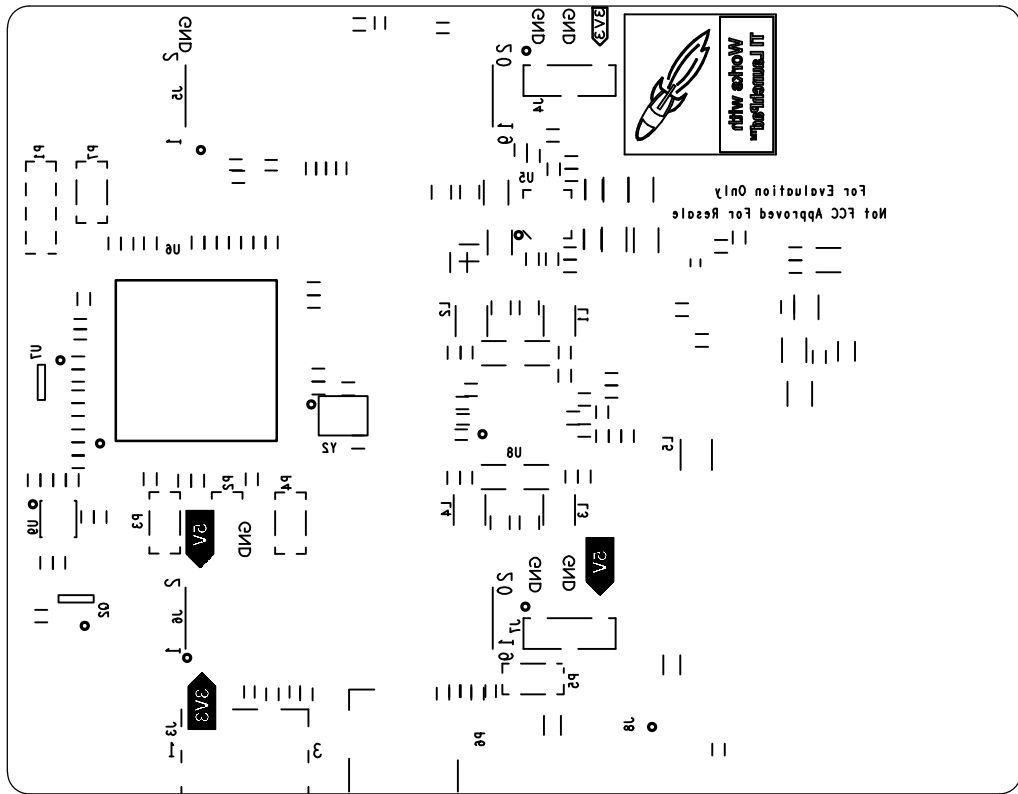
 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	LAYER-5 GROUND	1642-EVM Rev-A
	DATE: 02/MARCH/2017	




 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	LAYER - 6 BOTTOM	1642 - EVM Rev - A
	DATE: 02/MARCH/2017	




 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	SOLDERMASK TOP	1642-EVM Rev-A
	DATE: 02/MARCH/2017	



 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	SILKSCREEN BOTTOM	1642-EVM Rev-A
	DATE: 02/MARCH/2017	



 TEXAS INSTRUMENTS	TEXAS INSTRUMENTS	
	BOARD OUTLINE	1642-EVM Rev-A
	DATE: 02/MARCH/2017	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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